

Preliminary Amendment

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Docket No.: I431.169.101

Title: SEMICONDUCTOR HOUSINGS HAVING COUPLING COATINGS (as amended)

IN THE ABSTRACT

Please replace the Abstract with the following rewritten paragraph:

Abstract

~~Coupling organic coatings in semiconductor housings~~

A semiconductor housing having a coupling coating is disclosed. In one embodiment,
the semiconductor housing includes A leadframe for equipping with a semiconductor chip
(2) and for enveloping with a polymer material (4), to which a polymer layer (5) has been
applied. The polymer layer (5) has end groups (6) or (7) which possess particularly good
adhesion to the polymer material (4) or the surface of the flat conductor (1).

[~~Figure 1~~]